

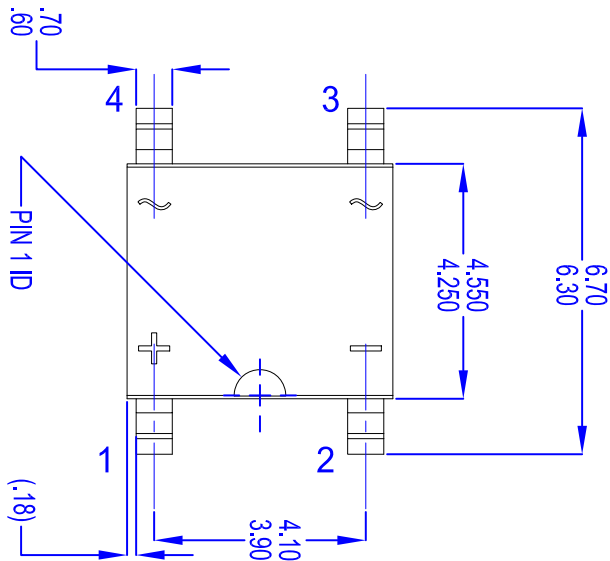
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

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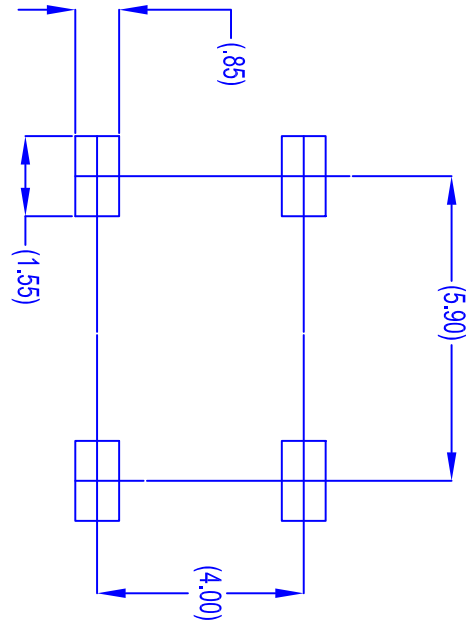


TSSOP4 5.0x4.4 / Micro-DIP
CASE 948BS
ISSUE O

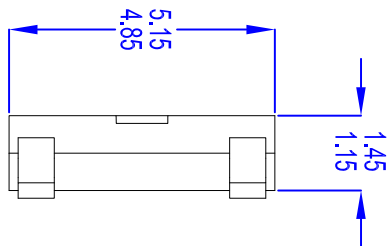
DATE 30 NOV 2016



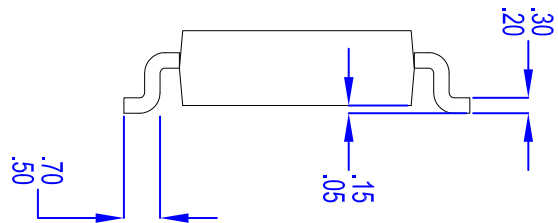
TOP VIEW



LAND PATTERN RECOMMENDATION



SIDE VIEW



END VIEW

NOTES:

- A. THIS PACKAGE DOES NOT CONFORM TO ANY REFERENCE STANDARD.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.

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